



#9

Attorney Docket No. 2269-4181US (96-0973.02/US)

DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:
My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD FOR USING DATA REGARDING MANUFACTURING PROCEDURES INTEGRATED CIRCUITS (IC'S) HAVE UNDERGONE, SUCH AS REPAIRS, TO SELECT PROCEDURES THE IC'S WILL UNDERGO, SUCH AS ADDITIONAL REPAIRS, the specification of which (check one):

- ☐ is attached hereto.
☒ was filed on August 31, 2000 as United States application serial no. 09/653,272 and was amended on _____.
☐ was filed on _____ as PCT international application no. _____ and was amended under PCT Article 19 on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to the patentability of the subject matter claimed in this application, as "materiality" is defined in Title 37, Code of Federal Regulations § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate or § 365(a) of any PCT international application(s) designating at least one country other than the United States of America listed below and on any attached continuation page and have also identified below and on any attached continuation page any foreign application for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America having a filing date before that of the application(s) on which priority is claimed.

Prior foreign/PCT application(s):

			Priority	Claimed
_____	_____	_____	_____	_____
(number)	(country)	(day/month/year filed)	Yes	No
_____	_____	_____	_____	_____
(number)	(country)	(day/month/year filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or § 365(c) of PCT international application(s) designating the United States of America listed below and on any attached continuation page and, insofar as the subject matter of each of the claims of this application is not disclosed in any such prior application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to

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Invention Title: METHOD FOR USING DATA REGARDING MANUFACTURING PROCEDURES INTEGRATED CIRCUITS (IC'S) HAVE UNDERGONE, SUCH AS REPAIRS, TO SELECT PROCEDURES THE IC'S WILL UNDERGO, SUCH AS ADDITIONAL REPAIRS

patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of such prior application and the national or PCT international filing date of this application:

09/292,655	April 15, 1999	patented
(application serial no.)	(filing date)	(status—pending, patented or abandoned)
08/871,015	June 6, 1997	patented
(application serial no.)	(filing date)	(status—pending, patented or abandoned)

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

_____	_____
(provisional application no.)	(filing date)

I hereby appoint the following Registered Practitioners to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,969
Laurence B. Bond, Reg. No. 30,549	Joseph A. Walkowski, Reg. No. 28,765
James R. Duzan, Reg. No. 28,393	H. Dickson Burton, Reg. No. 48,396
Allen C. Turner, Reg. No. 33,041	Edgar R. Cataxinos, Reg. No. 39,931
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Kevin K. Johanson, Reg. No. 38,506	Krista Weber Powell, Reg. No. 47,867
Bretton L. Crockett, Reg. No. 44,632	Tawni L. Wilhelm, Reg. No. 47,456
Bradley B. Jensen, Reg. No. 46,801	Andrew F. Nilles, Reg. No. 47,825
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Marcus S. Simon, Reg. No. 50,258	Trent N. Butcher, Reg. No. 51,518
G. Scott Dorland, Ph.D., Reg. No. 51,622	Jeffery M. Michelsen, Reg. No. 50,978
Michael L. Lynch, Reg. No. 30,871	Charles B. Brantley II, Reg. No. 38,086

Address all correspondence to: James R. Duzan, telephone no. (801) 532-1922.

TRASKBRITT, PC
P.O. Box 2550
Salt Lake City, Utah 84110

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first joint inventor: Salman Akram

Inventor's signature _____ Date _____
Residence: Boise, Idaho
Citizenship: Pakistan
Post Office Address: 1463 E. Regatta St., Boise, Idaho 83706

Full name of second joint inventor: Warren M. Farnworth

Inventor's signature _____ Date _____
Residence: Nampa, Idaho
Citizenship: U.S.A.
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Full name of third joint inventor: Derek J. Gochnour

Inventor's signature _____ Date _____
Residence: Boise, Idaho
Citizenship: U.S.A.
Post Office Address: 4823 S. Lippizan Avenue, Boise, Idaho 83709

Full name of fourth joint inventor: David R. Hembree

Inventor's signature _____ Date _____
Residence: Boise, Idaho
Citizenship: U.S.A.
Post Office Address: 11074 W. Edgehill Dr., Boise, Idaho 83709

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Full name of fifth joint inventor: Michael E. Hess

Inventor's signature _____ Date _____
Residence: Kuna, Idaho
Citizenship: U.S.A.
Post Office Address: 19137 So. Pleasant Valley, Kuna, Idaho 83634

Full name of sixth joint inventor: John O. Jacobson

Inventor's signature John O. Jacobson Date March 12, 2004
Residence: Boise, Idaho
Citizenship: U.S.A.
Post Office Address: 2149 Toluka Way, Boise, Idaho 83712

Full name of seventh joint inventor: James M. Wark

Inventor's signature _____ Date _____
Residence: Boise, Idaho
Citizenship: U.S.A.
Post Office Address: 5718 W. Drawbridge Drive, Boise, Idaho 83703

Full name of seventh joint inventor: Alan G. Wood

Inventor's signature _____ Date _____
Residence: Boise, Idaho
Citizenship: U.S.A.
Post Office Address: 1366 E. Versailles Ct., Boise, Idaho 83706



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Greg T. Warder, Reg. No. 50,208	Katherine A. Hamer, Reg. No. 47,628
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G. Scott Dorland, Ph.D., Reg. No. 51,622	Jeffery M. Michelsen, Reg. No. 50,978
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Full name of first joint inventor: Salman Akram

Inventor's signature Salman Akram Date 1/29/04
Residence: Boise, Idaho
Citizenship: ~~Pakistan~~ USA
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Full name of second joint inventor: Warren M. Farnworth

Inventor's signature Warren M. Farnworth Date 1-29-04
Residence: Nampa, Idaho
Citizenship: U.S.A.
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Full name of third joint inventor: Derek J. Gochmour

Inventor's signature Derek J. Gochmour Date 2/18/04
Residence: Boise, Idaho
Citizenship: U.S.A.
Post Office Address: 4823 S. Lippizan Avenue, Boise, Idaho 83709

Full name of fourth joint inventor: David R. Hembree

Inventor's signature David R. Hembree Date 1-29-04
Residence: Boise, Idaho
Citizenship: U.S.A.
Post Office Address: 11074 W. Edgehill Dr., Boise, Idaho 83709

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Full name of fifth joint inventor: Michael E. Hess

Inventor's signature Michael E. Hess Date 02/19/04

Residence: Kuna, Idaho

Citizenship: U.S.A.

Post Office Address: 19137 So. Pleasant Valley, Kuna, Idaho 83634

Full name of sixth joint inventor: John O. Jacobson

Inventor's signature _____ Date _____

Residence: Boise, Idaho

Citizenship: U.S.A.

Post Office Address: 2149 Toluka Way, Boise, Idaho 83712

Full name of seventh joint inventor: James M. Wark

Inventor's signature James M. Wark Date 1/29/04

Residence: Boise, Idaho

Citizenship: U.S.A.

Post Office Address: 5718 W. Drawbridge Drive, Boise, Idaho 83703

Full name of seventh joint inventor: Alan G. Wood

Inventor's signature Alan G. Wood Date 1/23/04

Residence: Boise, Idaho

Citizenship: U.S.A.

Post Office Address: 1366 E. Versailles Ct., Boise, Idaho 83706